Cell simulator sheet 6

AFE top and power in, sheet 4
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Power FETs sheet 2

Gauge and precharge FET sheet 5

Revision History

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PCB Number: PWR524
PCB Ver: A

PCB LOGO
Texas Instruments

Assembly Note
ZZ1
Final board is silkscreened after final board wash. Text shall be 8 pt. font. Text shall be variant name.

Assembly Note
ZZ2
These assemblies are ESD sensitive. ESD precautions shall be observed.

Assembly Note
ZZ3
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

Assembly Note
ZZ4
These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.

Assembly Note
ZZ5
Mount U1 to align with pin 1 of pattern

Assembly Note
ZZ6
Install shunts on referenced headers after final board wash

Assembly Note
ZZ7
Install adhesive feet per assembly variant

Assembly Note
ZZ8
Install adhesive feet per assembly variant

Assembly Note
ZZ9
Install label in silkscreen box after final board wash. Text shall be 8 pt. font. Text shall be variant name.

Assembly Note
ZZ10
These assemblies shall comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.

Assembly Note
ZZ11
Final board is silkscreened after final board wash. Text shall be 8 pt. font. Text shall be variant name.
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